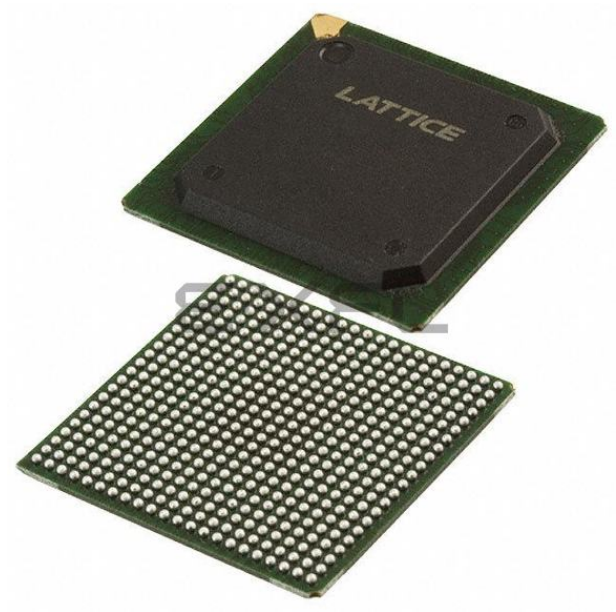
Lattice Semiconductor Corporation - LC5768MV-5F484C Datasheet



Welcome to E-XFL.COM

Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	24
Number of Macrocells	768
Number of Gates	-
Number of I/O	317
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc5768mv-5f484c

Product Line	Ordering Part Number	Product Status	Reference PCN
LC51024MV	LC51024MV-52F484C	Active / Orderable	
	LC51024MV-52FN484C		
	LC51024MV-75F484C		
	LC51024MV-75FN484C		
	LC51024MV-75F484I		
	LC51024MV-75FN484I		
	LC51024MV-52F672C		
	LC51024MV-52FN672C		
	LC51024MV-75F672C		
	LC51024MV-75FN672C		
	LC51024MV-75F672I		
	LC51024MV-75FN672I		
LC51024MB	LC51024MB-52F484C	**Discontinued**	PCN#09-10
	LC51024MB-52FN484C		
	LC51024MB-75F484C		
	LC51024MB-75FN484C		
	LC51024MB-75F484I		
	LC51024MB-75FN484I		
	LC51024MB-52F672C		
	LC51024MB-52FN672C		
	LC51024MB-75F672C		
	LC51024MB-75FN672C		
	LC51024MB-75F672I		
	LC51024MB-75FN672I		
LC51024MC	LC51024MC-52F484C	**Discontinued**	PCN#09-10
	LC51024MC-52FN484C		
	LC51024MC-75F484C		
	LC51024MC-75FN484C		
	LC51024MC-75F484I		
	LC51024MC-75FN484I		
	LC51024MC-52F672C		
	LC51024MC-52FN672C		
	LC51024MC-75F672C		
	LC51024MC-75FN672C		
	LC51024MC-75F672I		
	LC51024MC-75FN672I		

ispXPLD™ 5000MX Family

3.3V, 2.5V and 1.8V In-System Programmable
eXpanded Programmable Logic Device XPLD™ Family

February 2010 **Data Sheet**

Features

- **Flexible Multi-Function Block (MFB) Architecture**
  - SuperWIDE™ logic (up to 136 inputs)
  - Arithmetic capability
  - Single- or Dual-port SRAM
  - FIFO
  - Ternary CAM
- **sysCLOCK™ PLL Timing Control**
  - Multiply and divide between 1 and 32
  - Clock shifting capability
  - External feedback capability
- **sysIO™ Interfaces**
  - LVCMOS 1.8, 2.5, 3.3V
    - Programmable impedance
    - Hot-socketing
    - Flexible bus-maintenance (Pull-up, pull-down, bus-keeper, or none)
    - Open drain operation
  - SSTL 2, 3 (I & II)
  - HSTL (I, III, IV)
  - PCI 3.3
  - GTL+
  - LVDS
  - LVPECL
  - LVTTL
- **Expanded In-System Programmability (ispXP™)**
  - Instant-on capability
  - Single chip convenience
  - In-System Programmable via IEEE 1532 Interface
  - Infinitely reconfigurable via IEEE 1532 or sysCONFIG™ microprocessor interface
  - Design security
- **High Speed Operation**
  - 4.0ns pin-to-pin delays, 300MHz f_{MAX}
  - Deterministic timing
- **Low Power Consumption**
  - Typical static power: 20 to 50mA (1.8V), 30 to 60mA (2.5/3.3V)
  - 1.8V core for low dynamic power
- **Easy System Integration**
  - 3.3V (5000MV), 2.5V (5000MB) and 1.8V (5000MC) power supply operation
  - 5V tolerant I/O for LVCMOS 3.3 and LVTTL interfaces
  - IEEE 1149.1 interface for boundary scan testing
  - sysIO quick configuration
  - Density migration
  - Multiple density and package options
  - PQFP and fine pitch BGA packaging
  - Lead-free package options

Table 1. ispXPLD 5000MX Family Selection Guide

	ispXPLD 5256MX	ispXPLD 5512MX	ispXPLD 5768MX	ispXPLD 51024MX
Macrocells	256	512	768	1,024
Multi-Function Blocks	8	16	24	32
Maximum RAM Bits	128K	256K	384K	512K
Maximum CAM Bits	48K	96K	144K	192K
sysCLOCK PLLs	2	2	2	2
t_{PD} (Propagation Delay)	4.0ns	4.5ns	5.0ns	5.2ns
t_S (Register Set-up Time)	2.2ns	2.8ns	2.8ns	3.0ns
t_{CO} (Register Clock to Out Time)	2.8ns	3.0ns	3.2ns	3.7ns
f_{MAX} (Maximum Operating Frequency)	300MHz	275MHz	250MHz	250MHz
Functional Gates	75K	150K	225K	300K
I/Os	141	149/193/253	193/317	317/381
Packages	256 fpBGA	208 PQFP 256 fpBGA 484 fpBGA	256 fpBGA 484 fpBGA	484 fpBGA 672 fpBGA

5000MX. Incoming signals may connect to the global routing pool or the registers in the MFBs. An Output Sharing Array (OSA) increases the number of I/O available to each MFB, allowing a complete function high-performance access to the I/O. There are four clock pins that drive four global clock nets within the device. Two sysCLOCK PLLs are provided to allow the synthesis of new clocks and control of clock skews.

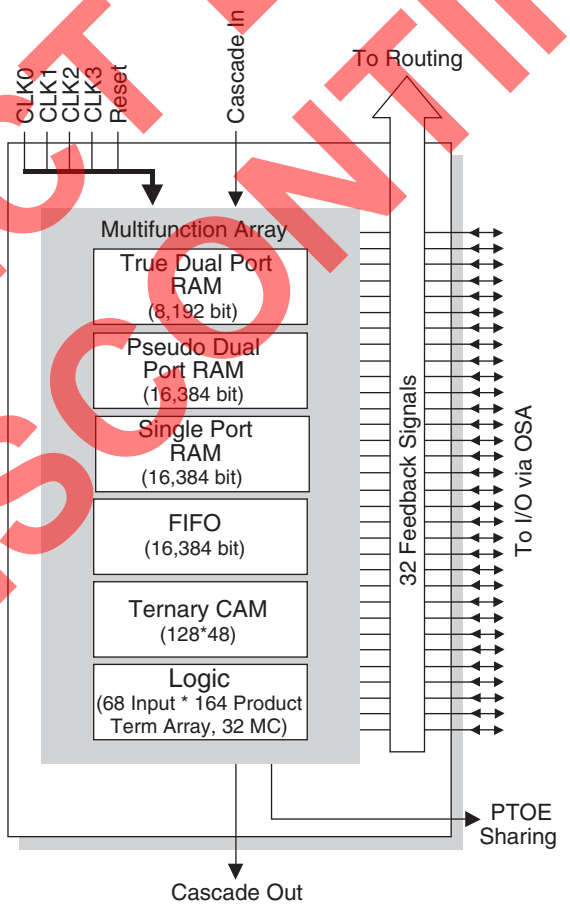
Multi-Function Block (MFB)

Each MFB in the ispXPLD 5000MX architecture can be configured in one of the six following modes. This provides a flexible approach to implementing logic and memory that allows the designer to achieve the mix of functions that are required for a particular design, maximizing resource utilization. The six modes supported by the MFB are:

- SuperWIDE Logic Mode
- True Dual-port SRAM Mode
- Pseudo Dual-port SRAM Mode
- Single-port SRAM Mode
- FIFO Mode
- Ternary CAM Mode

The MFB consists of a multi-function array and associated routing. Depending on the chosen functions the multi-function array uses up to 68 inputs from the GRP and the four global clock and reset signals. The array outputs data along with certain control functions to the macrocells. Output signals can be routed internally for use elsewhere in the device and to the sysIO banks for output. Figure 2 shows the block diagram of the MFB. The various configurations are described in more detail in the following sections.

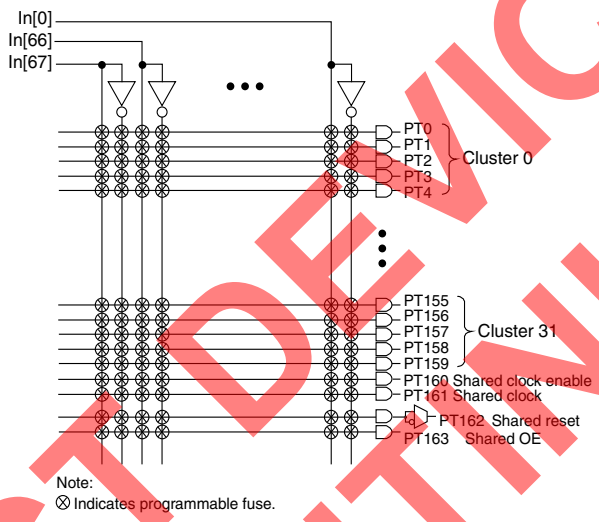
Figure 2. MFB Block Diagram



AND-Array

The programmable AND-Array consists of 68 inputs and 164 output product terms. The 68 inputs from the GRP are used to form 136 lines in the AND-Array (true and complement of the inputs). Each line in the array can be connected to any of the 164 output product terms via a wired AND. Each of the 160 logic product terms feed the Dual-OR Array with the remaining four control product terms feeding the Shared PT Clock, Shared PT Clock Enable, Shared PT Reset and Shared PT OE. Starting with PT0 sets of five product terms form product term clusters. There is one product term cluster for every macrocell in the MFB. In addition to the four control product terms, the first, third, fourth and fifth product terms of each cluster can be used as a PTOE, PT Clock, PT Preset and PT Reset, respectively. Figure 5 is a graphical representation of the AND-Array.

Figure 5. AND Array

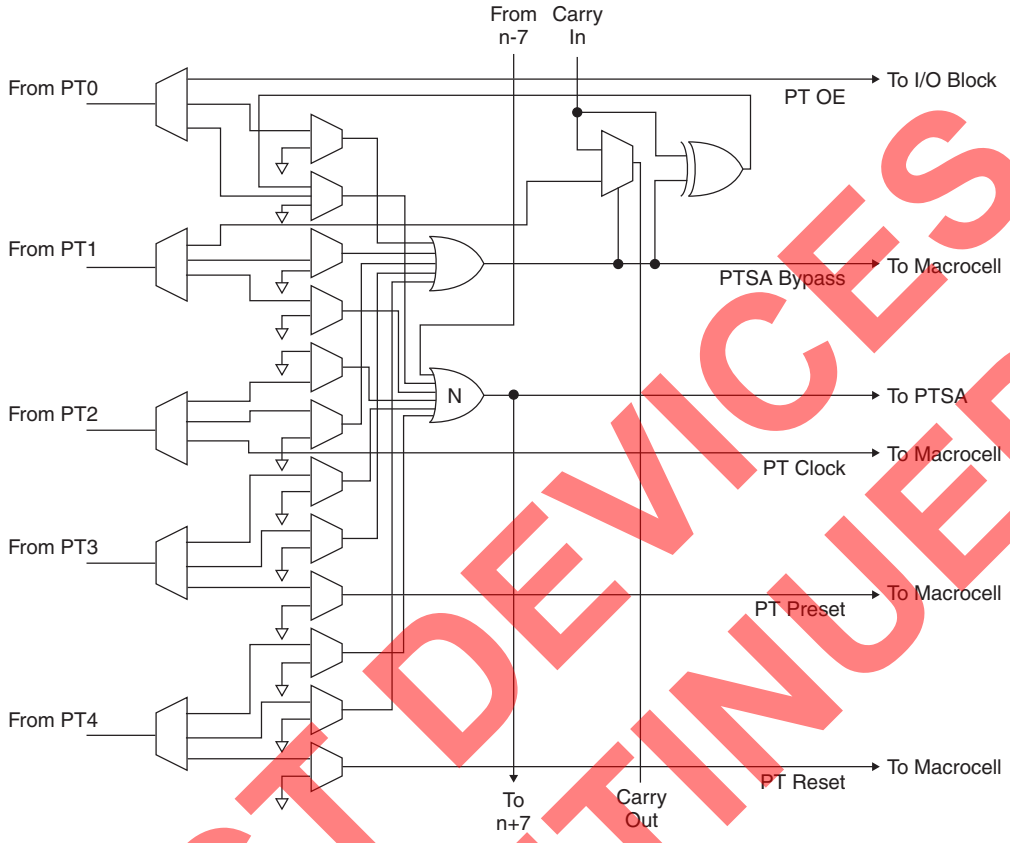


Dual-OR Array (Including Arithmetic Support)

The Dual-OR Array consists of 64 OR gates. There are two OR gates per macrocell in the MFB. These OR gates are referred to as the Expandable PTSA OR gate and the PTSA-Bypass OR gate. The PTSA-Bypass OR gate receives its five inputs from the combination of product terms associated with the product term cluster. The PTSA-Bypass OR gate feeds the macrocell directly for fast narrow logic. The Expandable PTSA OR gate receives five inputs from the combination of product terms associated with the product term cluster. It also receives an additional input from the Expanded PTSA OR gate of the N-7 macrocell, where N is the number of the macrocell associated with the current OR gate. The Expandable PTSA OR gate feeds the PTSA for sharing with other product terms and the N+7 Expandable PTSA OR gate. This allows cascading of multiple OR gates for wide functions. There is a small timing adder for each level of expansion. Figure 6 is a graphical representation of the Dual-OR Array.

The Dual-OR PT sharing array also contains logic to aid in the efficient implementation of arithmetic functions. This logic takes Carry In and allows the generation of Carry Out along with a SUM signal. Subtractors can be implemented using the two's complement method. Carry is propagated from macrocells 0 to macrocell 31. Macrocell zero can have its carry input connected to the carry output of macrocell 31 in an adjacent MFB or it can be set to zero or one. If a macrocell is not used in an arithmetic function carry can bypass it. The carry chain flows is the same as that for PT cascading.

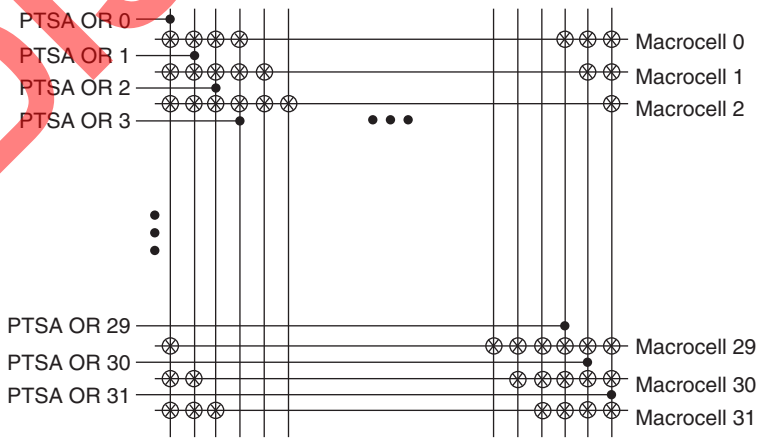
Figure 6. Dual-OR PT Sharing Array



Product Term Sharing Array

The Product Term Sharing Array (PTSA) consists of 32 inputs from the Dual-OR Array (Expandable PTSA OR) and 32 outputs directly to the macrocells. Each output is the OR term of any combination of the seven Expandable PTSA OR terms connected to that output. Every Nth macrocell is connected to N-3, N-2, N-1, N, N+1, N+2 and N+3 PTSA OR terms via a programmable connection. This wraps around the logic, for example, Macrocell 0 gets its logic from 29, 30, 31, 0, 1, 2, 3. The Expandable PTSA OR used in conjunction with the PTSA allows wide functions to be implemented easily and efficiently. Without using the Expandable PTSA OR capability, the greatest number of product terms that can be included in a single function with one pass of delay is 35. Up to 160 product terms can be included in a single function through the use of the expandable PTSA OR capability. Figure 7 shows the graphical representation of the PTSA.

Figure 7. Product Term Sharing Array (PTSA)



Single-Port SRAM Mode

In Single-Port SRAM Mode the multi-function array is configured as a single-port SRAM. In this mode one ports accesses 16,384-bits of memory. Data widths of 1, 2, 4, 8, 16 and 32 are supported by the MFB. Figure 11 shows the block diagram of the single-port SRAM.

Write data, address, chip select and read/write signals are always synchronous (registered.) The output data signals can be synchronous or asynchronous. Reset is asynchronous. All signals share a common clock, clock enable, and reset. Table 7 shows the possible sources for the clock, clock enable and reset signals.

Figure 11. Single-Port SRAM Block Diagram

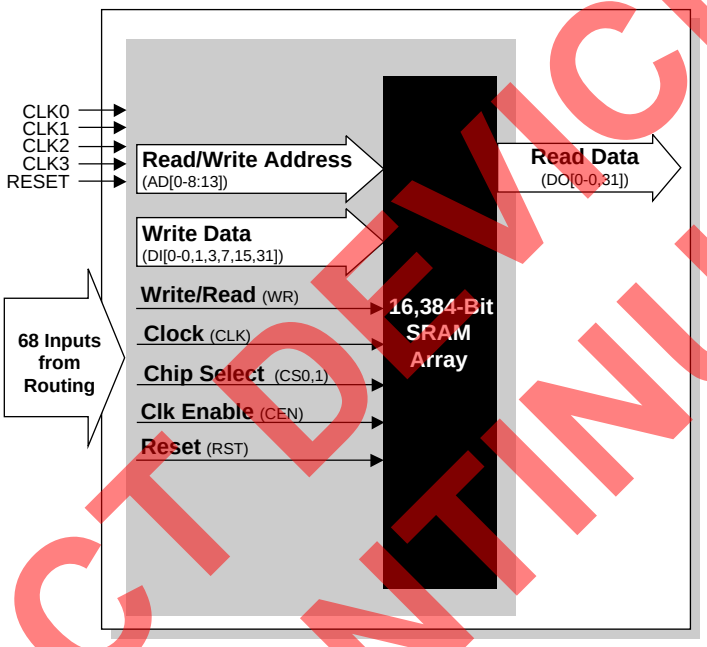


Table 7. Register Clock, Clock Enable, and Reset in Single-Port SRAM Mode

Register	Input	Source
Address, Write Data, Read Data, Read/ Write, and Chip Select	Clock	CLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	CEN or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired.

CAM Mode

In CAM Mode the multi-function array is configured as a Ternary Content Addressable Memory (CAM). CAM behaves like a reverse memory where the input is data and the output is an address. It can be used to perform a variety of high-performance look-up functions. As such, CAM has two modes of operation. In write or update mode the CAM behaves as a RAM and data is written to the supplied address. In read or compare operations data is supplied to the CAM and if this matches any of the data in the array the Match and Multiple Match (if there is more than one match) flags are set to true and the lowest address with matching data is output. The CAM contains 128 entries of 48 bits. Figure 13 shows the block diagram of the CAM.

To further enhance the flexibility of the CAM a mask register is available. If enabled during updates, bits corresponding with those set to 1 in the mask register are not updated. If enabled during compare operations, bits corresponding to those set to 1 in the mask register are not included in the compare. A write don't care signal allows don't cares to be programmed into the CAM if desired. Like other write operations the mask register controls this.

The write/comp data, write address, write enable, write chip select, and write don't care signals are synchronous. The CAM Output signals, match flag, and multimatch flag can be synchronous or asynchronous. The Enable mask register input is not latched but must meet setup and hold times relative to the write clock. All inputs must use the same clock and clock enable signals. All outputs must use the same clock and clock enable signals. Reset is common for both inputs and outputs. Table 9 shows the allowable sources for clock, clock enable, and reset for the various CAM registers.

Figure 13. CAM Mode

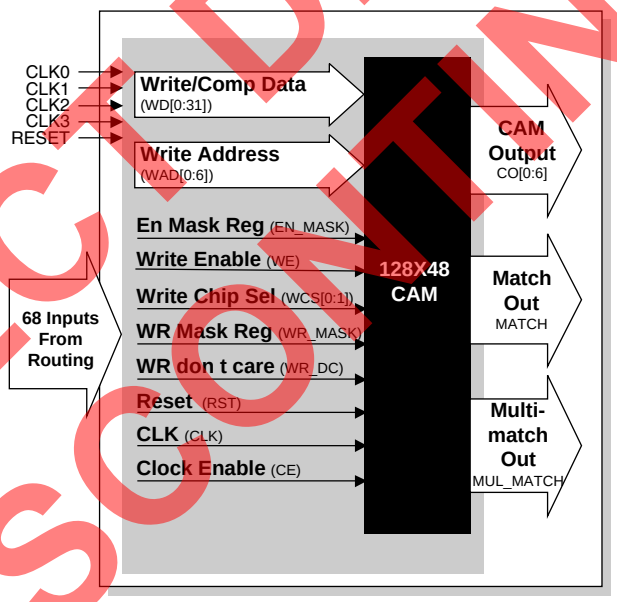


Table 9. Register Clocks, Clock Enables, and Initialization in CAM Mode

Register	Input	Source
Write data, Write address, Enable mask register, Write enable, write chip select, and write don't care, CAM Output, Match, and Multimatch	Clock	CLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	WE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired

Absolute Maximum Ratings[1, 2, 3]

	ispXPLD 5000MC 1.8V	ispXPLD 5000MB/V 2.5V/3.3V
Supply Voltage (V_{CC})	-0.5 to 2.5V	-0.5 to 5.5V
PLL Supply Voltage (V_{CCP})	-0.5 to 2.5V	-0.5 to 5.5V
Output Supply Voltage (V_{CCO})	-0.5 to 4.5V	-0.5 to 4.5V
IEEE 1149.1 TAP Supply Voltage (V_{CCJ})	-0.5 to 4.5V	-0.5 to 4.5V
Input Voltage Applied[4, 5]	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C
Junction Temperature (T_J) with Power Applied	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied (while programming, following the programming specifications).
2. Compliance with the Lattice Thermal Management document is required.
3. All voltages referenced to GND.
4. Overshoot and Undershoot of -2V to (V_{IHMAX} +2) volts not to exceed 6V is permitted for a duration of <20ns.
5. A maximum of 64 I/Os per device with V_{IN} > 3.6V is allowed.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Supply Voltage for 1.8V Devices (ispXPLD 5000MC)	1.65	1.95	V
	Supply Voltage for 2.5V Devices (ispXPLD 5000MB)	2.3	2.7	V
	Supply Voltage for 3.3V Devices (ispXPLD 5000MV)	3	3.6	V
V_{CCP}	PLL Block Supply Voltage for PLL 1.8V Devices	1.65	1.95	V
	PLL Block Supply Voltage for PLL 2.5V Devices	2.3	2.7	V
	PLL Block Supply Voltage for PLL 3.3V Devices	3	3.6	V
T_J	Junction Temperature (Commercial Operation)	0	90	C
	Junction Temperature (Industrial Operation)	-40	105	C

E²CMOS Erase Reprogram Specifications

Parameter	Min.	Max.	Units
Erase/Reprogram Cycle[1]	1,000	—	Cycles

1. Valid over commercial temperature range.

Hot Socketing Characteristics[1, 2, 3, 4]

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O Leakage Current	0 ð V_{IN} ð 3.0V	—	+/-50	+/-800	µA

1. Insensitive to sequence of V_{CC} and V_{CCO} when V_{CCO}þð 1.0V. For V_{CCO} > 1.0V, V_{CC} min must be present. However, assumes monotonic rise/fall rates for V_{CC} and $V_{CCO,}$ provided (V_{IN} - V_{CCO})þð 3.6V.
2. 0 ð V_{CC} ð V_{CC} (MAX), 0 ð V_{CCO} ð V_{CCO} (MAX)
3. I_{DK} is additive to I_{PU}, I_{PD} or I_{BH}. Device defaults to pull-up until non-volatile cells are active.
4. LVTTL, LVCMOS only.

Supply Current

Symbol	Parameter	Condition	Min.	Typ.[3]	Max.	Units
ispXPLD 5256						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	26	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	26	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	16	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA
ispXPLD 5512						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	33	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	33	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	22	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA
ispXPLD 5768						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	40	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	40	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	30	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA

sysIO Single Ended DC Electrical Characteristics

Over Recommended Operating Conditions

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max (V)	V_{OH} Min (V)	I_{OL}[2] (mA)	I_{OH}[2] (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVCMOS 3.3	-0.3	0.8	2.0	5.5	0.4	2.4	20, 16, 12, 8, 5.33, 4	-20, -16, -12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	5.5	0.4	2.4	4	-4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCO} - 0.4	16, 12, 8, 5.33, 4	-16, -12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVCMOS 1.8[1, 3]	-0.3	0.68	1.07	3.6	0.4	V_{CCO} - 0.4	8	-8
LVCMOS 1.8[3]	-0.3	0.68	1.07	3.6	0.4	V_{CCO} -0.4	12, 5.33, 4	-12, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
PCI 3.3[4]	-0.3	1.08	1.5	3.6	0.1 V_{CCO}	0.9 V_{CCO}	1.5	-0.5
AGP-1X[4]	-0.3	1.08	1.5	3.6	0.1 V_{CCO}	0.9 V_{CCO}	1.5	-0.5
SSTL3 class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCO} - 1.1	8	-8
SSTL3 class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCO} - 0.9	16	-16
SSTL2 class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCO} - 0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCO} - 0.43	15.2	-15.2
CTT 3.3	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	V_{REF} - 0.4	V_{REF} + 0.4	8	-8
CTT 2.5	-0.3	V_{REF} - 0.3	V_{REF} + 0.2	3.6	V_{REF} - 0.4	V_{REF} + 0.4	8	-8
HSTL class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} - 0.4	8	-8
HSTL class III	-0.3	V_{REF} - 0.2	V_{REF} + 0.1	3.6	0.4	V_{CCO} - 0.4	24	-8
HSTL class IV	-0.3	V_{REF} - 0.3	V_{REF} + 0.1	3.6	0.4	V_{CCO} - 0.4	48	-8
GTL+	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.6	n/a	36	n/a

1. Software default setting.
2. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed n*8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.
3. For 1.8V devices (ispXPLD 5000MC) these specifications are V_{IL} = 0.35 * V_{CC} and V_{IH} = 0.65 * V_{CC}.
4. For 1.8V devices (ispXPLD 5000MC) these specifications are V_{IL} = 0.3 * V_{CC} * 3.3/1.8, V_{IH} = 0.5 * V_{CC} * 3.3/1.8.

sysIO Differential DC Electrical Characteristics

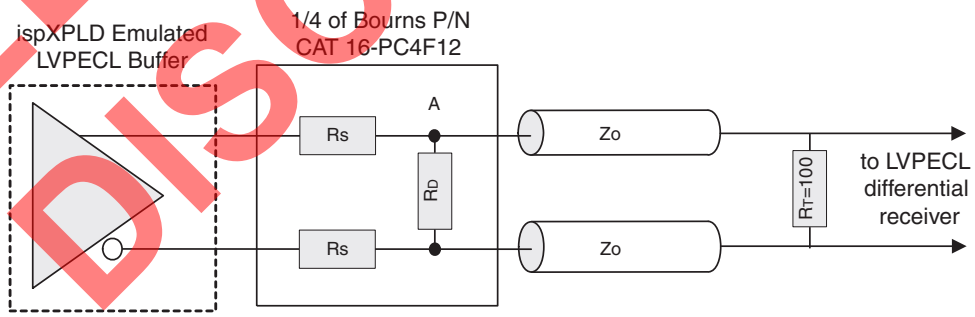
Over Recommended Operating Conditions

Parameter	Description	Test Conditions	Min.	Typ.	Max.
LVDS					
V_{INP}	Input Voltage		0V	—	2.4V
V_{THD}	Differential Input Threshold	0.2 ð V_{CM} ð 1.8V	+/-100mV	—	—
I_{IN}	Input Current	Power On	—	—	+/-10uA
V_{OH}	Output High Voltage for V_{OP} or V_{OM}	RT = 100 Ohm	—	1.38V	1.60V
V_{OL}	Output Low Voltage for V_{OP} or V_{OM}	RT = 100 Ohm	0.9V	1.03V	—
V_{OD}	Output Voltage Differential	(V_{OP} - V_{OM}), R_T = 100 Ohm	250mV	350mV	450mV
ΔV_{OD}	Change in V_{OD} Between High and Low		—	—	50mV
V_{OS}	Output Voltage Offset	(V_{OP} - V_{OM})/2, R_T = 100 Ohm	1.125V	1.20V	1.375V
ΔV_{OS}	Change in V_{OS} Between H and L		—	—	50mV
I_{OSD}	Output Short Circuit Current	V_{OD} = 0V Driver outputs shorted	—	—	24mA

LVPECL[1]								
DC Parameter	**Parameter Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
V_{CCO}		**3.0**		**3.3**		**3.6**		**V**
V_{IH}	Input Voltage High	1.49	2.72	1.49	2.72	1.49	2.72	V
V_{IL}	Input Voltage Low	0.86	2.125	0.86	2.125	0.86	2.125	V
V_{OH}	Output Voltage High	1.7	2.11	1.92	2.28	2.03	2.41	V
V_{OL}	Output Voltage Low	0.96	1.27	1.06	1.43	1.3	1.57	V
V_{DIFF}[2]	Differential Input voltage	0.3	—	0.3	—	0.3	—	V

1. These values are valid at the output of the source termination pack as shown above with 100-ohm differential load only (see Figure 19). The V_{OH} levels are 200mV below the standard LVPECL levels and are compatible with devices tolerant of the lower common mode ranges.
2. Valid for 0.2 ð V_{CM} ð 1.8V

Figure 19. LVPECL Driver with Three Resistor Pack



ispXPLD 5000MX Family Internal Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays													
t_{IN}	Input Buffer Delay	—	—	0.70	—	0.91	—	0.96	—	1.11	—	1.30	ns
t_{GCLK_IN}	Global Clock Input Buffer Delay	—	—	0.40	—	0.35	—	0.35	—	0.35	—	0.55	ns
t_{RST}	Global RESET Pin Delay	—	—	3.77	—	4.24	—	4.71	—	4.71	—	7.07	ns
t_{GOE}	Global OE Pin Delay	—	—	1.98	—	2.66	—	2.34	—	2.87	—	3.27	ns
t_{BUF}	Delay through Output Buffer	—	—	1.16	—	1.30	—	1.45	—	1.60	—	2.17	ns
t_{EN}	Output Enable Time	—	—	2.52	—	2.84	—	3.16	—	3.63	—	4.23	ns
t_{DIS}	Output Disable Time	—	—	1.92	—	2.40	—	2.40	—	2.40	—	3.60	ns
Routing Delays													
t_{ROUTE}	Delay through SRP	—	—	1.95	—	2.06	—	2.34	—	2.24	—	3.66	ns
t_{INREG}	Input Buffer to Macrocell Register Delay	—	—	0.60	—	0.60	—	0.60	—	0.47	—	1.63	ns
t_{PTSA}	Product Term Sharing Array Delay	—	—	0.50	—	0.50	—	0.53	—	0.83	—	1.34	ns
t_{FBK}	Internal Feedback Delay	—	—	0.19	—	0.02	—	0.39	—	0.03	—	0.60	ns
t_{GCLK}	Global Clock Tree Delay	—	—	0.52	—	0.32	—	0.72	—	0.82	—	0.78	ns
t_{BCLK}	Block PT Clock Delay	—	—	0.12	—	0.14	—	0.15	—	0.15	—	0.23	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	—	0.12	—	0.14	—	0.15	—	0.15	—	0.23	ns
t_{PLL_DELAY}	Programmable PLL Delay Increment	—	—	0.30	—	0.30	—	0.30	—	0.30	—	0.30	ns
t_{BSR}	Block PT Reset Delay	—	—	0.72	—	0.81	—	0.90	—	0.94	—	1.35	ns
t_{PTSR}	Macrocell PT Set/ Reset Delay	—	—	0.60	—	0.75	—	0.75	—	0.75	—	1.13	ns
t_{LPTOE}	Macrocell PT OE Delay	—	—	0.83	—	1.19	—	1.04	—	1.52	—	1.31	ns
t_{SPTOE}	Segment PT OE Delay	—	—	0.83	—	1.19	—	1.04	—	1.52	—	1.31	ns
t_{OSA}	Output Sharing Array Delay	—	—	0.80	—	0.90	—	1.00	—	1.00	—	1.50	ns
t_{PTOE}	Global PT OE Delay	—	—	0.83	—	1.04	—	1.04	—	1.04	—	1.56	ns
t_{PDB}	5-PT Bypass Propagation Delay	—	—	0.20	—	0.23	—	0.25	—	0.25	—	0.38	ns
t_{PDI}	Macrocell Propagation Delay	—	—	0.50	—	0.93	—	0.72	—	0.72	—	1.04	ns

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
$t_{CAMWMSKS}$	Write Mask Register Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{CAMWMSKH}$	Write Mask Register Setup Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMRSTO}$	Reset to CAM Output Delay	—	—	3.30	—	3.30	—	4.13	—	4.13	—	4.29	ns
$t_{CAMRSTR}$	Reset Recovery Time	—	1.20	—	1.20	—	1.50	—	1.50	—	1.56	—	ns
$t_{CAMRSTPW}$	Reset Pulse Width	—	0.14	—	0.14	—	0.18	—	0.18	—	0.19	—	ns
CAM – Compare Mode													
$t_{CAMDATAS}$	Data Setup Time before Clock	—	-0.41	—	-0.41	—	-0.33	—	-0.33	—	-0.31	—	ns
$t_{CAMDATAH}$	Data Hold Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMENMSKS}$	Enable Mask Register Setup Time before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{CAMENMSKH}$	Enable Mask Register Setup Time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{CAMCASC}$	CAM Width Expansion Delay	—	—	0.40	—	0.40	—	0.50	—	0.50	—	0.51	ns
t_{CAMCO}	Clock to Output (Address Out) Delay	—	—	6.19	—	6.13	—	6.81	—	6.61	—	9.63	ns
$t_{CAMMATCH}$	Clock to Match Flag Delay	—	—	6.19	—	6.13	—	6.07	—	6.61	—	10.22	ns
$t_{CAMMMATCH}$	Clock to Multi-Match Flag Delay	—	—	5.50	—	5.50	—	6.38	—	6.38	—	7.72	ns
$t_{CAMRSTFLAG}$	CAM Reset to Flags Delay	—	—	3.16	—	3.16	—	3.95	—	3.95	—	4.11	ns
Single Port RAM													
$t_{SPADDDATA}$	Address to Data Delay	—	—	5.97	—	5.97	—	5.97	—	5.97	—	7.76	ns
t_{SPMSS}	Memory Select Setup Before Clock Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{SPMSH}	Memory Select Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{SPCES}	Clock Enable Setup before Clock Time	—	2.30	—	2.30	—	2.30	—	2.30	—	9.80	—	ns
t_{SPCEH}	Clock Enable Hold time after Clock Time	—	-2.95	—	-2.95	—	-2.95	—	-2.95	—	-2.27	—	ns
t_{SPADDS}	Address Setup before Clock Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns

ispXP sysCONFIG Port Timing Specifications

Symbol	Timing Parameter	Min.	Max.	Units
sysCONFIG Write Cycle Timing				
t_{SUCS}	Input setup time of CS to CCLK rise	10	—	ns
t_{HCS}	Hold time of CS to CCLK rise	1	—	ns
t_{SUWD}	Input setup time of write data to CCLK rise	10	—	ns
t_{HWD}	Hold time of write data to CCLK rise	0	—	ns
t_{PRGM}	Low time to reset device SRAM	5	50	ns
t_{DINIT}	INIT delay time	—	5	ms
t_{IODISS}	User I/O disable	—	—	ns
t_{IOENSS}	User I/O enable	—	—	ns
t_{WH}	Write clock High pulse width	18	—	ns
t_{WL}	Write clock Low pulse width	18	—	ns
f_{MAXW}	Write f_{MAX}	—	27	MHz
sysCONFIG Read Cycle Timing				
t_{HREAD}	Hold time of READ to CCLK rise	1	—	ns
t_{SUREAD}	Input setup time of READ High to CCLK rise	15	—	ns
t_{RH}	READ clock high pulse width	18	—	ns
t_{RL}	READ clock low pulse width	18	—	ns
f_{MAXR}	Read f_{MAX}	—	27	MHz
t_{CORD}	Clock to out for read data	—	25	ns

Power Estimation Equations

ICC = ICC_DC + IMFB_CPLD + IMFB_ SRAM/PDPRAM/FIFO + IMFB_DPRAM + IMFB_CAM + IPLL_D

ICC_DC
Use the appropriate value for 5000MC (1.8V power supply) or 5000MV/B (2.5V/3.3V power supply) from the data sheet.

IMFB_CPLD
= ((**K0** * CPLD MFB inputs + **K1** * CPLD Logical Product Terms + **K2** * CPLD GRP from MFB + **K3** * CPLD GRP from IFB) * AF+ **K4**) * FREQ / 1000µA/mA

IMFB_CAM
= CAM Memory MFBs * ((FREQ * **K8**) + **K9**) (CAM operating in typical mode)

IMFB_ SRAM/PDPRAM/FIFO
= (WR_ PERCENT * (**K1** + WR_ PERCENT * 8 * **K0** + **K10** + **K11**) + RD_ PERCENT * (**K1** + 128 * RD_PERCENT * **K0** + 8 * OSW_PERCENT * **K2**)) * SRAM/PDPRAM/FIFO Memory MFBs * FREQ / 1000µA/mA

IMFB_ DPRAM
= (WR_ PERCENT * (2 * **K1** + 2 * WR_ PERCENT * 8 * **K0** + **K10** + **K11**) + RD_ PERCENT * (2 * **K1** + 2 * 128 * RD_PERCENT * **K0** + 8 * OSW_PERCENT * **K2**)) * DPRAM Memory MFBs * FREQ / 1000µA/mA

IPLL_D
= **K5** * PLL_FREQ * number of PLLs used. IPPL_D is the PLL digital component of the VCC supply current.

Analog portion of PLL supply current consumption, from PLL power pin:

IPLL_A = (**K6** * PLL_FREQ + **K7**) * number of PLLs used

Notes:

- ICC = Current consumption of VCC power supply (mA)
- ICC-DC = ICC DC component – Current consumption at 0Mhz (mA)
- IMFB_CPLD = CPLD (non-memory logic) current consumption (mA)
- IMFB_SRAM/PDPRAM/FIFO = Current consumption for SRAM, PDPRAM, and FIFO (mA)
- IMFB_DPRAM = Current consumption for DPRAM (mA)
- IMFB_CAM = Current consumption for CAM (mA)
- IPLL_D = PLL Current consumption of digital VCC power supply (mA)
- IPLL_A = PLL analog power pin current consumption (VCCP pin)

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
1	-	C28	D14	-	C29	P5	U8
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	15P	C26	D16	-	C27	T4	V6
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	15N	C24	D18	-	C25	T5	V7
-	-	GND	-	-	-	GND	GND
1	16P	C22	D20	-	C23	R4	Y5
-	-	VCC	-	-	-	VCC	VCC
1	16N	C20	D22	-	C21	N6	AA5
1	17P	C18	-	-	C19	R5	Y6
1	17N	C16	-	-	C17	P6	Y7
1	18P	C14	-	-	C15	—	AA6
1	18N	C12	-	-	C13	—	AA7
1	19P	C10	-	-	C11	—	W7
1	19N	C8	-	-	C9	M7	V8
1	20P	C6	-	-	C7	T6	W8
1	20N	C4	-	-	C5	R6	U9
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
-	-	CFG0	-	-	-	L8	U10
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	21P	C0	C16	A16	C1	T7	AB7
1	21N	D30	C17	A17	D31	R7	AA8
1	22P	D28	C18	A18	D29	N7	AB8
1	22N	D26	C19	A19	D27	P7	AB9
1	23P	D24	C20	A20	D25	T8	W9
1	23N	D22	C21	A21	D23	R8	Y9
1	24P	D20	C22	A22	D21	M8	AB10
1	24N	D18	C23	A23	D19	P8	AA10
1	-	D16/VREF1	-	-	D17	L9	W10
1	25P	D14	C24	A24	D15	N8	Y10
1	25N	D12	C25	A25	D13	M9	Y11
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	26P	D10	C26	A26	D11	N10	V9
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	26N	D8	C27	A27	D9	T9	V10
1	27P	D6	C28	A28	D7	T10	AA11
-	-	GND	-	-	-	GND	GND
1	27N	D4	C29	A29	D5	R9	AB11
-	-	VCC	-	-	-	VCC	VCC
1	28P	D2	C30	A30	D3	P9	U11
1	28N	D0	C31	A31	D1	N9	V11
2	29P	E0	F0	H0	E1	T11	AB12
-	-	VCC	-	-	-	VCC	VCC

ispXPLD 5000MC (1.8V) Commercial Devices (Continued)

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5768MC	LC5768MC-5F256C	768	1.8	5.0	fpBGA	256	193	C
	LC5768MC-75F256C	768	1.8	7.5	fpBGA	256	193	C
	LC5768MC-5F484C	768	1.8	5.0	fpBGA	484	317	C
	LC5768MC-75F484C	768	1.8	7.5	fpBGA	484	317	C
LC51024MC	LC51024MC-52F484C	1024	1.8	5.2	fpBGA	484	317	C
	LC51024MC-75F484C	1024	1.8	7.5	fpBGA	484	317	C
	LC51024MC-52F672C	1024	1.8	5.2	fpBGA	672	381	C
	LC51024MC-75F672C	1024	1.8	7.5	fpBGA	672	381	C

ispXPLD 5000MC (1.8V) Industrial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MC	LC5256MC-5F256I	256	1.8	5.0	fpBGA	256	141	I
	LC5256MC-75F256I	256	1.8	7.5	fpBGA	256	141	I
LC5512MC	LC5512MC-75Q208I	512	1.8	7.5	PQFP	208	149	I
	LC5512MC-75F256I	512	1.8	7.5	fpBGA	256	193	I
	LC5512MC-75F484I	512	1.8	7.5	fpBGA	484	253	I
LC5768MC	LC5768MC-75F256I	768	1.8	7.5	fpBGA	256	193	I
	LC5768MC-75F484I	768	1.8	7.5	fpBGA	484	317	I
LC51024MC	LC51024MC-75F484I	1024	1.8	7.5	fpBGA	484	317	I
	LC51024MC-75F672I	1024	1.8	7.5	fpBGA	672	381	I

ispXPLD 5000MB (2.5V) Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MB	LC5256MB-4F256C	256	2.5	4.0	fpBGA	256	141	C
	LC5256MB-5F256C	256	2.5	5.0	fpBGA	256	141	C
	LC5256MB-75F256C	256	2.5	7.5	fpBGA	256	141	C
LC5512MB	LC5512MB-45Q208C	512	2.5	4.5	PQFP	208	149	C
	LC5512MB-75Q208C	512	2.5	7.5	PQFP	208	149	C
	LC5512MB-45F256C	512	2.5	4.5	fpBGA	256	193	C
	LC5512MB-75F256C	512	2.5	7.5	fpBGA	256	193	C
	LC5512MB-45F484C	512	2.5	4.5	fpBGA	484	253	C
	LC5512MB-75F484C	512	2.5	7.5	fpBGA	484	253	C
LC5768MB	LC5768MB-5F256C	768	2.5	5.0	fpBGA	256	193	C
	LC5768MB-75F256C	768	2.5	7.5	fpBGA	256	193	C
	LC5768MB-5F484C	768	2.5	5.0	fpBGA	484	317	C
	LC5768MB-75F484C	768	2.5	7.5	fpBGA	484	317	C
LC51024MB	LC51024MB-52F484C	1024	2.5	5.2	fpBGA	484	317	C
	LC51024MB-75F484C	1024	2.5	7.5	fpBGA	484	317	C
	LC51024MB-52F672C	1024	2.5	5.2	fpBGA	672	381	C
	LC51024MB-75F672C	1024	2.5	7.5	fpBGA	672	381	C

ispXPLD 5000MB (2.5V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MB	LC5256MB-4FN256C	256	2.5	4.0	Lead-free fpBGA	256	141	C
	LC5256MB-5FN256C	256	2.5	5.0	Lead-free fpBGA	256	141	C
	LC5256MB-75FN256C	256	2.5	7.5	Lead-free fpBGA	256	141	C
LC5512MB	LC5512MB-45QN208C	512	2.5	4.5	Lead-free PQFP	208	149	C
	LC5512MB-75QN208C	512	2.5	7.5	Lead-free PQFP	208	149	C
	LC5512MB-45FN256C	512	2.5	4.5	Lead-free fpBGA	256	193	C
	LC5512MB-75FN256C	512	2.5	7.5	Lead-free fpBGA	256	193	C
	LC5512MB-45FN484C	512	2.5	4.5	Lead-free fpBGA	484	253	C
	LC5512MB-75FN484C	512	2.5	7.5	Lead-free fpBGA	484	253	C
LC5768MB	LC5768MB-5FN256C	768	2.5	5.0	Lead-free fpBGA	256	193	C
	LC5768MB-75FN256C	768	2.5	7.5	Lead-free fpBGA	256	193	C
	LC5768MB-5FN484C	768	2.5	5.0	Lead-free fpBGA	484	317	C
	LC5768MB-75FN484C	768	2.5	7.5	Lead-free fpBGA	484	317	C
LC51024MB	LC51024MB-52FN484C	1024	2.5	5.2	Lead-free fpBGA	484	317	C
	LC51024MB-75FN484C	1024	2.5	7.5	Lead-free fpBGA	484	317	C
	LC51024MB-52FN672C	1024	2.5	5.2	Lead-free fpBGA	672	381	C
	LC51024MB-75FN672C	1024	2.5	7.5	Lead-free fpBGA	672	381	C

ispXPLD 5000MB (2.5V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MB	LC5256MB-5FN256I	256	2.5	5.0	Lead-free fpBGA	256	141	I
	LC5256MB-75FN256I	256	2.5	7.5	Lead-free fpBGA	256	141	I
LC5512MB	LC5512MB-75QN208I	512	2.5	7.5	Lead-free PQFP	208	149	I
	LC5512MB-75FN256I	512	2.5	7.5	Lead-free fpBGA	256	193	I
	LC5512MB-75FN484I	512	2.5	7.5	Lead-free fpBGA	484	253	I
LC5768MB	LC5768MB-75FN256I	768	2.5	7.5	Lead-free fpBGA	256	193	I
	LC5768MB-75FN484I	768	2.5	7.5	Lead-free fpBGA	484	317	I
LC51024MB	LC51024MB-75FN484I	1024	2.5	7.5	Lead-free fpBGA	484	317	I
	LC51024MB-75FN672I	1024	2.5	7.5	Lead-free fpBGA	672	381	I

ispXPLD 5000MV (3.3V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MV	LC5256MV-4FN256C	256	3.3	4.0	Lead-free fpBGA	256	141	C
	LC5256MV-5FN256C	256	3.3	5.0	Lead-free fpBGA	256	141	C
	LC5256MV-75FN256C	256	3.3	7.5	Lead-free fpBGA	256	141	C

ispXPLD 5000MV (3.3V) Lead-Free Commercial Devices (Continued)

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5512MV	LC5512MV-45QN208C	512	3.3	4.5	Lead-free PQFP	208	149	C
	LC5512MV-75QN208C	512	3.3	7.5	Lead-free PQFP	208	149	C
	LC5512MV-45FN256C	512	3.3	4.5	Lead-free fpBGA	256	193	C
	LC5512MV-75FN256C	512	3.3	7.5	Lead-free fpBGA	256	193	C
	LC5512MV-45FN484C	512	3.3	4.5	Lead-free fpBGA	484	253	C
	LC5512MV-75FN484C	512	3.3	7.5	Lead-free fpBGA	484	253	C
LC5768MV	LC5768MV-5FN256C	768	3.3	5.0	Lead-free fpBGA	256	193	C
	LC5768MV-75FN256C	768	3.3	7.5	Lead-free fpBGA	256	193	C
	LC5768MV-5FN484C	768	3.3	5.0	Lead-free fpBGA	484	317	C
	LC5768MV-75FN484C	768	3.3	7.5	Lead-free fpBGA	484	317	C
LC51024MV	LC51024MV-52FN484C	1024	3.3	5.2	Lead-free fpBGA	484	317	C
	LC51024MV-75FN484C	1024	3.3	7.5	Lead-free fpBGA	484	317	C
	LC51024MV-52FN672C	1024	3.3	5.2	Lead-free fpBGA	672	381	C
	LC51024MV-75FN672C	1024	3.3	7.5	Lead-free fpBGA	672	381	C

ispXPLD 5000MV (3.3V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MV	LC5256MV-5FN256I	256	3.3	5.0	Lead-free fpBGA	256	141	I
	LC5256MV-75FN256I	256	3.3	7.5	Lead-free fpBGA	256	141	I
LC5512MV	LC5512MV-75QN208I	512	3.3	7.5	Lead-free PQFP	208	149	I
	LC5512MV-75FN256I	512	3.3	7.5	Lead-free fpBGA	256	193	I
	LC5512MV-75FN484I	512	3.3	7.5	Lead-free fpBGA	484	253	I
LC5768MV	LC5768MV-75FN256I	768	3.3	7.5	Lead-free fpBGA	256	193	I
	LC5768MV-75FN484I	768	3.3	7.5	Lead-free fpBGA	484	317	I
LC51024MV	LC51024MV-75FN484I	1024	3.3	7.5	Lead-free fpBGA	484	317	I
	LC51024MV-75FN672I	1024	3.3	7.5	Lead-free fpBGA	672	381	I

For Further Information

In addition to this data sheet, the following technical notes may be helpful when designing with the ispXPLD 5000MX family:

- TN1000 – sysIO Usage Guidelines for Lattice Devices
- TN1003 – sysCLOCK PLL Usage Guide for ispXPGA, ispGDX2, ispXPLD and ispMACH 5000VG Devices
- TN1031 – Power Estimation in ispXPLD 5000MX Devices
- TN1030 – Using Memory in ispXPLD 5000MX Devices
- TN1026 – ispXP Configuration Usage Guidelines

Revision History

Date	Version	Change Summary
—	—	Previous Lattice releases.
December 2003	07	Added ispXPLD 5768MX information (supply current, timings, power consumption, power estimation coefficients, memory coefficients, logic signal connections, ordering part numbers).
		Updated ispXPLD 5000MX timing numbers (version v.1.7).
		Added lead-free package designator.
		Removed ispXPLD 5000MC industrial temperature grade ordering part numbers.
January 2004	08	Lead-free package release for the ispXPLD 5000MC and 5000MV devices.
		Timing model parameter tCOi correction - Maximum specification instead of Minimum (no changes in the timing numbers).
March 2004	08.1	Updated the MFB Cascade Chain table for the ispXPLD 5256MX device.
May 2004	09	Updated the ispXPLD 5000MX timig numbers (version v.1.8) ispXPLD 5256MC, 5512MC and 51024MC industrial temperature grade devices release
		Updated typical supply current data and condition.
		ispXPLD 5256MX 256-fpBGA logic signal connection tables: Removed internal signal description for ball H5 and G14.
August 2004	10	Added footnote "1, page 49. These inputs should not toggle during power up for proper power-up configuration." to CCLK and READ.
		Added ispXPLD 5768MC Industrial grade OPNs (Conventional and Lead-Free).
October 2004	10.1	Figure 19, LVPECL Driver with Three Resistor Pack has been updated (ispXPLD LVPECL Buffer changed to ispXPLD Emulated LVPECL Buffer)
November 2004	11	Added ispXPLD 5000MB (2.5V) Lead-Free Ordering Part Numbers.
December 2004	11.1	Pin name RESETB has been updated to RESET.
March 2005	12	208-PQFP Lead-free package release for the ispXPLD 5512MV/B/C devices.
April 2005	12.1	Page 23, clarification of footnote regarding IDK specification.
March 2006	12.2	Signal description for RESET has been updated.
April 2009	12.3	Ordering Information section has been updated to describe alternate LC5768MB/MV top side marking format.
February 2010	12.4	References to "system gates" changed to "functional gates."